

## **Mechanical Information**

## **Package Information & Dimensions**

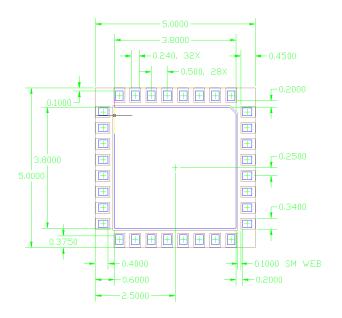
Material:

RoHS-compliant Contact plating: Electrolytic plated Au over Ni

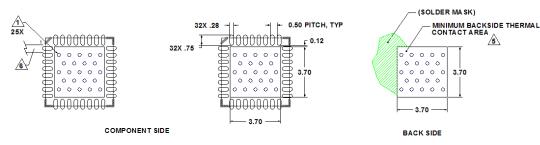
Package Marking:

Part number - TQM8M9077 Year, week, country code - YYWW CCCC Assembly code - AaXXXX





## **Mounting Configuration**



- 1 GROUND/THERMAL VIAS ARE CRITICAL FOR THE PROPER PERFORMANCE OF THIS DEVICE. VIAS SHOULD USE A .35mm (#80/.0135") DIAMETER DRILL AND HAVE A FINAL, PLATED THRU DIAMETER OF .25mm (.010").
- 2. ADD AS MUCH COPPER AS POSSIBLE TO INNER AND OUTER LAYERS NEAR THE PART TO ENSURE OPTIMAL THERMAL PERFORMANCE.
- TO ENSURE RELIABLE OPERATION, DEVICE GROUND PADDLE-TO-GROUND PAD SOLDER JOINT IS CRITICAL.
- 4. ADD MOUNTING SCREWS NEAR THE PART TO FASTEN THE BOARD TO A HEATSINK. ENSURE THAT THE GROUND/THERMAL VIA REGION CONTACTS THE HEATSINK.
- 5 DO NOT PUT SOLDER MASK ON THE BACK SIDE OF THE PC BOARD IN THE REGION WHERE THE BOARD CONTACTS THE HEATSINK.
- 6 RF TRACE WIDTH DEPENDS UPON THE PC BOARD MATERIAL AND CONSTRUCTION
- 8. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.

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